Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

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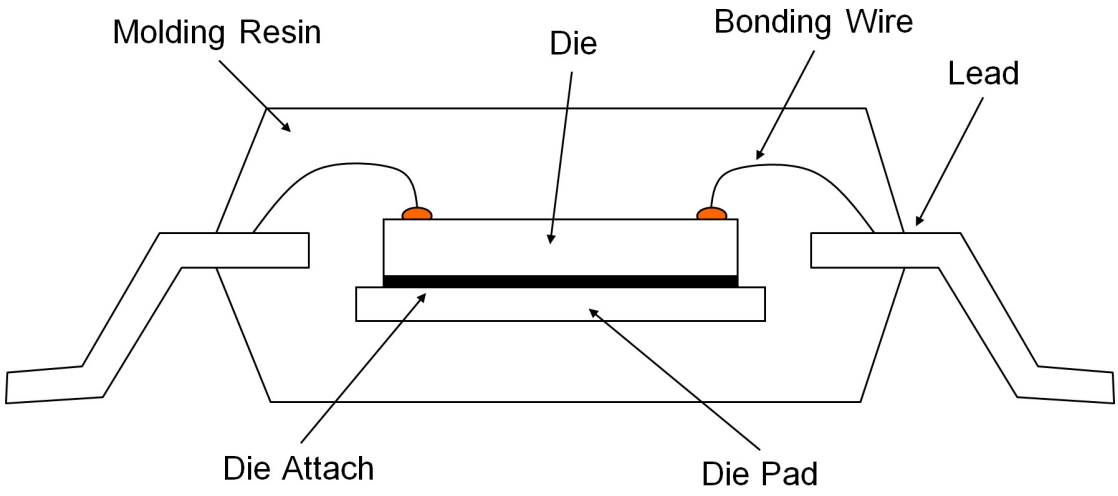
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

Package Information : SOP8

1. Package Information

Package Name	SOP8
Type	SOP
Pin Count	8
Outline Dimension Drowing No.	EX112-5001-2
Package Weight [g]	0.084
Lead Finish	Pure Tin
MSL Level	Level1

2. Package Structure



3. Packing Specification

3.1 Packing form, Quantity, PIN1 Orientation

Packing Form		Tape&Reel
Packing Quantity	[pcs]	2,500
PIN 1 Orientation		E2

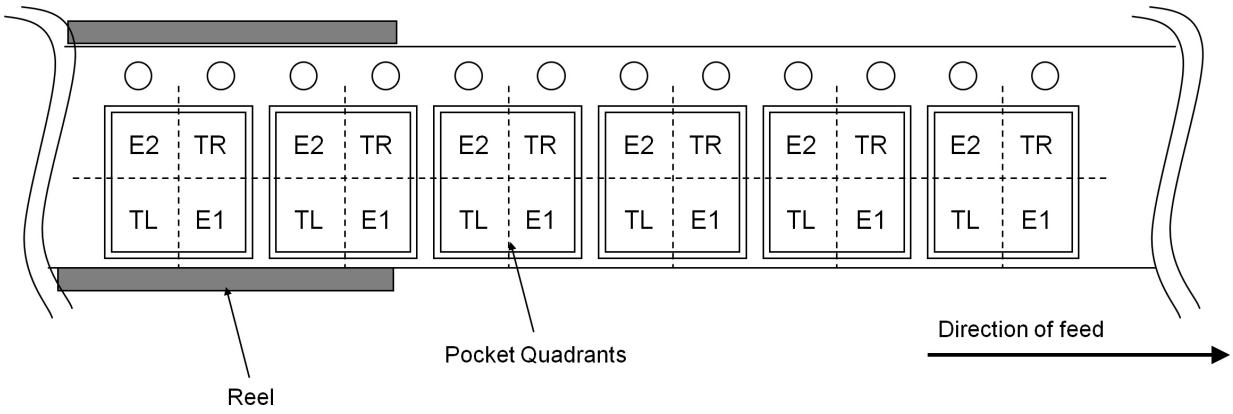


Fig.1 Quadrant Assignments for PIN 1 Orientation in Tape

E2 : PIN1 is placed to the top left corner. TR : PIN1 is placed to the top right corner.

TL : PIN1 is placed to the lower left. E1 : PIN1 is placed to the lower right.

3.2 Use material

Item	Material
Embossed carrier tape	PS
Cover tape	PET+PE
Reel	PS
Air cap	PE
Unit box	Cardboard
Shipping box	Cardboard

3.3 Leader specification

No component pockets are 320 mm or more.

3.4 Trailer specification

No component pockets are 80 mm or more. Tape is free from reel.

3.5 Peelback strength

Cover tape peelback strength is 0.2 N to 0.7 N.

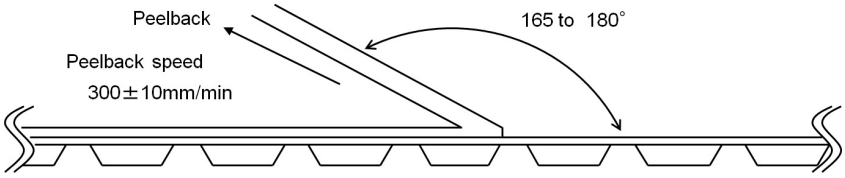


Fig. 2 Test method

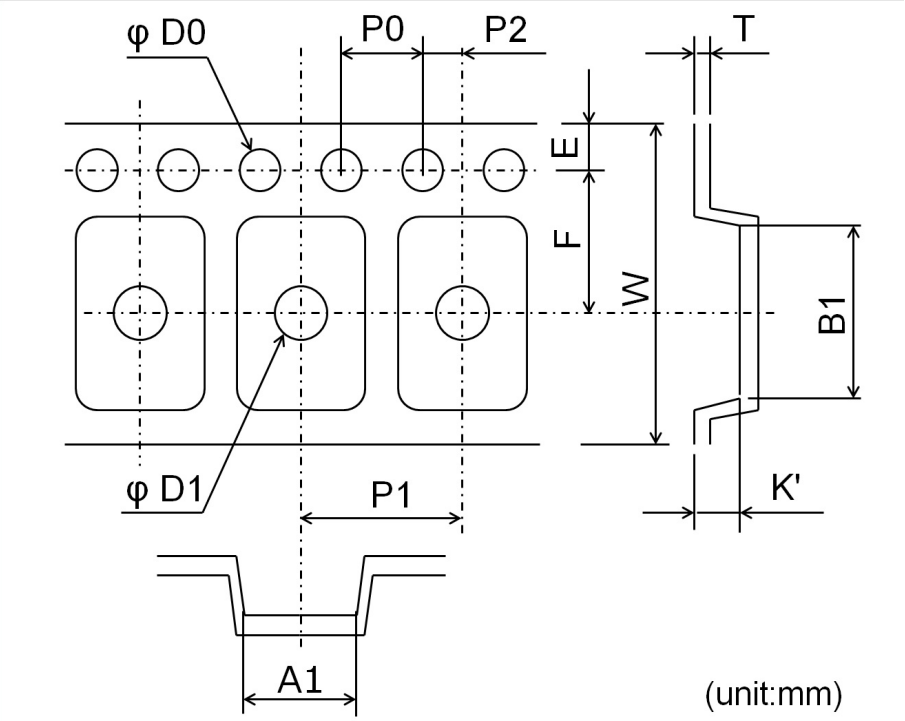
3.6 Missing Ics

(1) No consecutive dropouts.

(2) A maximun 0.1 % of specified number of products in each packing may be missing.

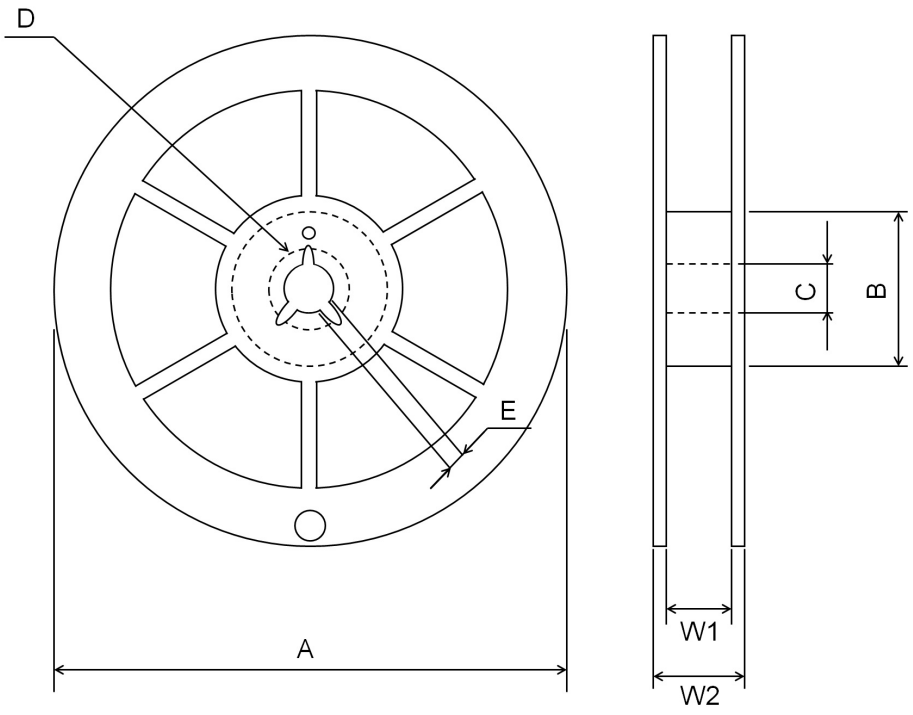
3.7 Tape and Reel Specification

3.7.1 Tape Dimension



	Tape Dimension	Tape Tolerance
A1	6.80	±0.1
B1	5.50	±0.1
D0	φ1.5	+0.1/-0
D1	φ1.5	MIN
E	1.75	±0.1
F	5.50	±0.1
K'	2.00	±0.1
P0	4.00	±0.1
P1	8.00	±0.1
P2	2.00	±0.1
T	0.30	-
W	12.0	±0.3

3.7.2 Reel Dimension

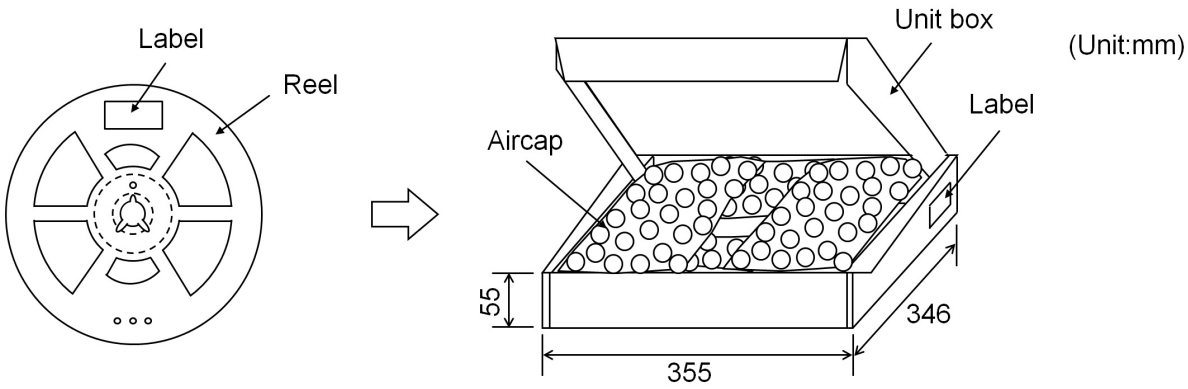


(unit:mm)

	Reel Dimension	Reel Tolerance
A	330	±2.0
B	80	±1.0
C	13	±0.2
D	21	±0.8
E	2	±0.5
W1	13.5	±1.0
W2	17.5	±1.0

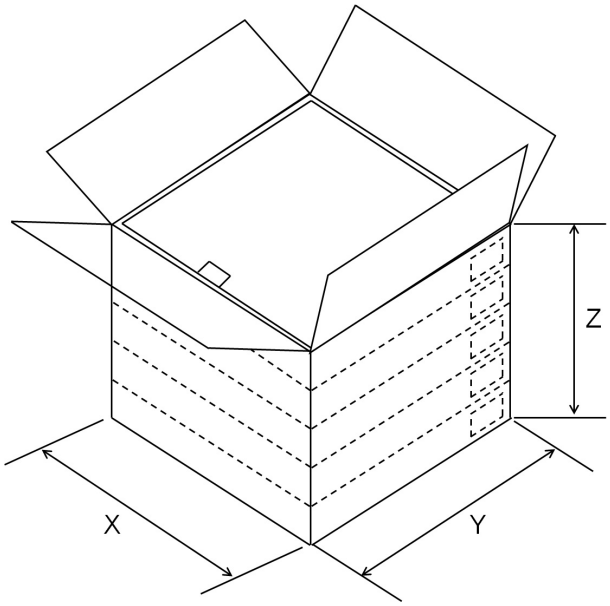
3.8 Packing Method

1 reel(s) or less per unit box



3.9 Packing Style

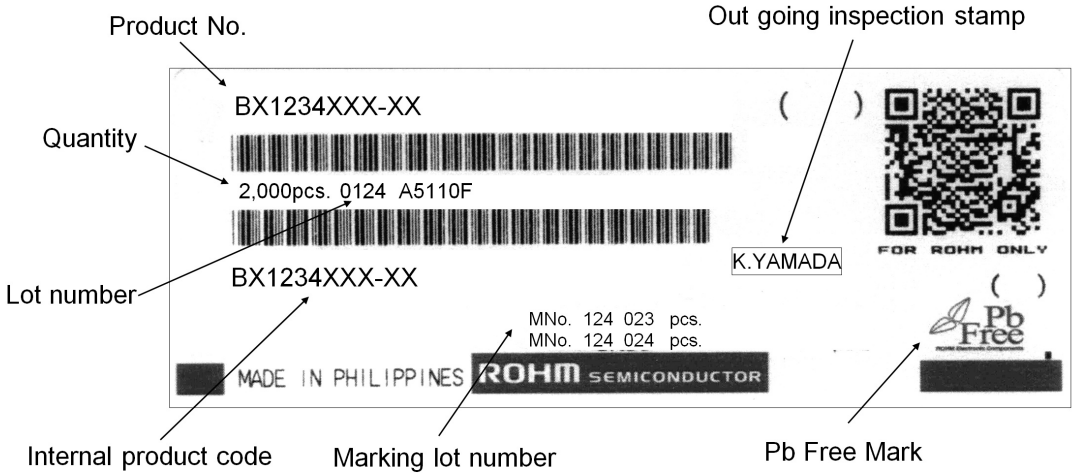
5 unit boxes or less per shipping box



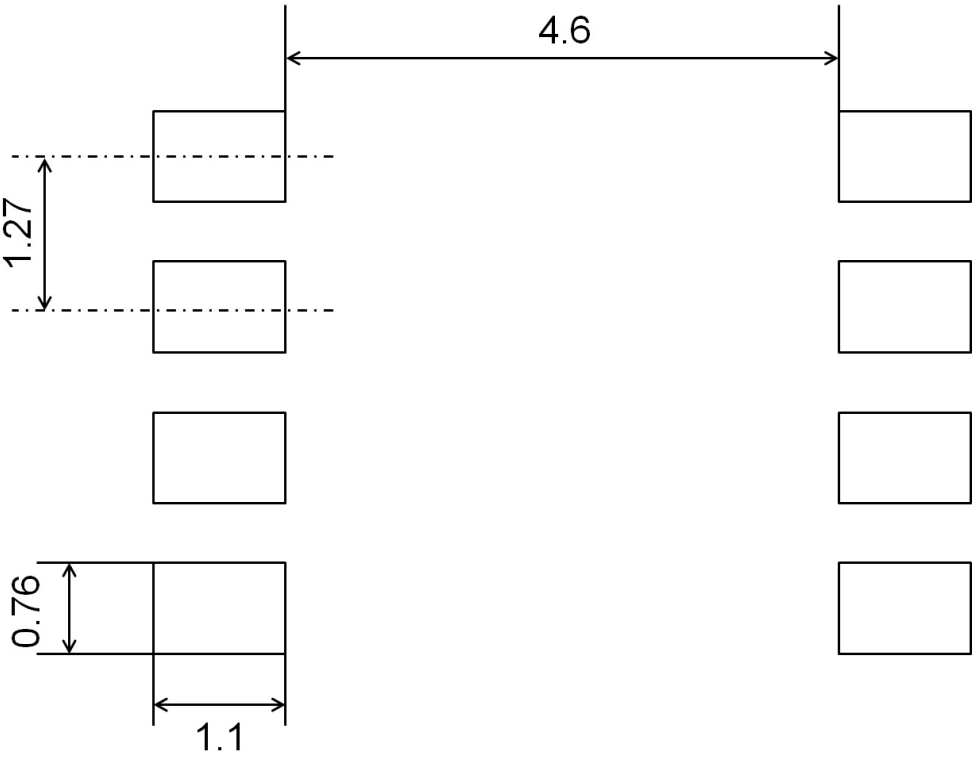
(unit:mm)

Shipping Box Dimension	
X	372
Y	368
Z	305

3.10 Label Specification



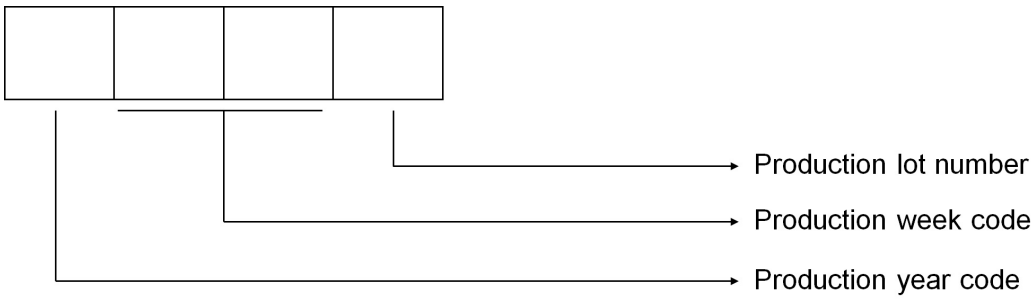
4. Footprint dimensions



(unit:mm)

In actual design, please optimize in accordance with the situation of your board design and soldering condition.

5. Marking Specification



6. Storage conditions

6.1 Storage environment

Recommended storage conditions

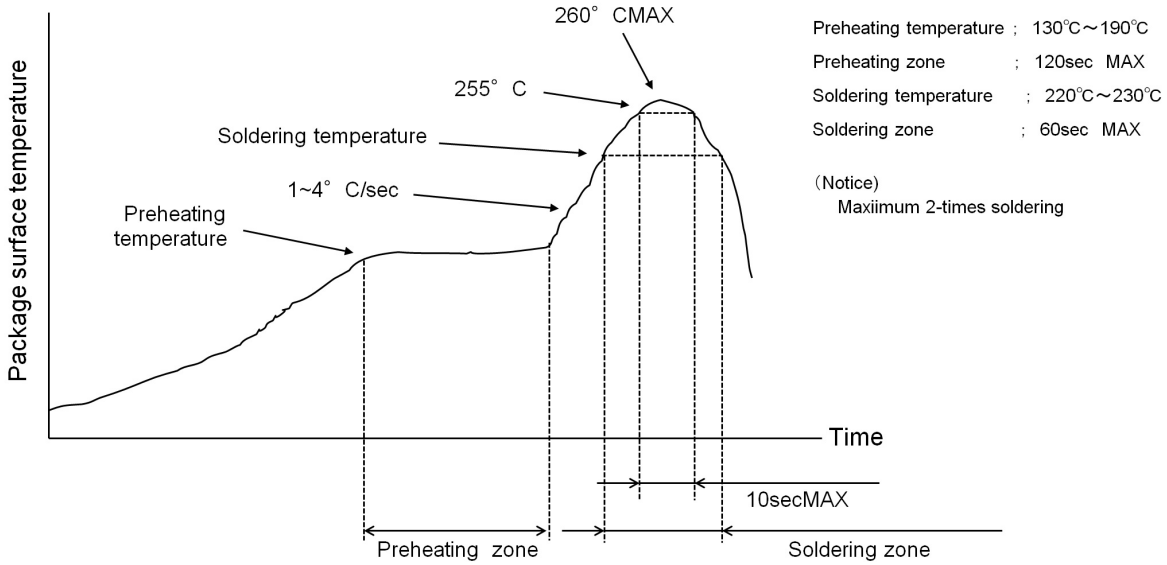
	Min.	Max.	Unit
Temperature	5	30	°C
Humidity	40	70	% RH

6.2 Storage period

	Min.	Max.	Unit
Storage period	-	1	year

7. Soldering conditions

7.1 Recommended temperature profile for reflow



7.2 Recommended condition for wave soldering

Preheating temperature	:	120 °C to 150 °C
Preheating time	:	60 sec MAX
Soldering temperature	:	260 °C ± 3 °C
Soldering time	:	12 sec MAX

Notes for wave soldering

(1)Soldering time is provided for total soldering time in case of dual wave soldering.

(2) Do not use other soldering methods with wave soldering.

(3) Recommend to clean the board to eliminate flux, solder waste, and other impurities for reliability, after soldering.

(4) Optimize soldering condition to prevent solder bridging.

7.3 Recommended condition for solder iron

Solder iron temperature	:	380 °C or less
Mounting time	:	4 sec or less

Notes

1) The information contained herein is subject to change without notice.

2) Before you use our Products, please contact our sales representative and verify the latest specifications :

3) Although ROHM is continuously working to improve product reliability and quality, semiconductors can break down and malfunction due to various factors.
Therefore, in order to prevent personal injury or fire arising from failure, please take safety measures such as complying with the derating characteristics, implementing redundant and fire prevention designs, and utilizing backups and fail-safe procedures. ROHM shall have no responsibility for any damages arising out of the use of our Poducts beyond the rating specified by ROHM.

4) Examples of application circuits, circuit constants and any other information contained herein are provided only to illustrate the standard usage and operations of the Products. The peripheral conditions must be taken into account when designing circuits for mass production.

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7) The Products specified in this document are not designed to be radiation tolerant.

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